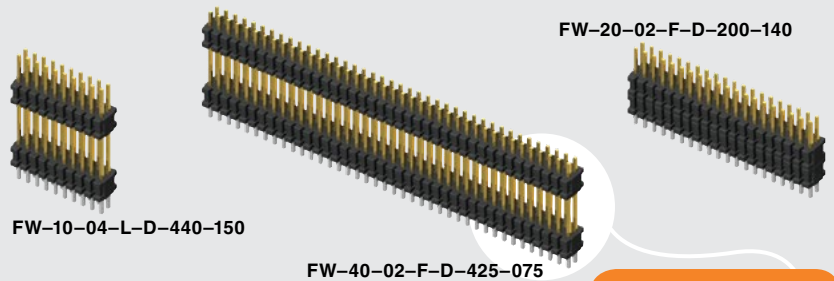


FLEX STACK



(1.27 mm) .050"

FW-TH SERIES

THROUGH-HOLE MICRO BOARD STACKER

SPECIFICATIONS

For complete specifications see www.samtec.com?FW-TH

Insulator Material: Black Liquid Crystal Polymer
Terminal Material: Phosphor Bronze
Plating: Sn or Au over 50 μm (1.27 μm) Ni
Operating Temp Range: -55 °C to +125 °C
RoHS Compliant: Yes

PROCESSING

Lead-Free Solderable: Yes

RECOGNITIONS

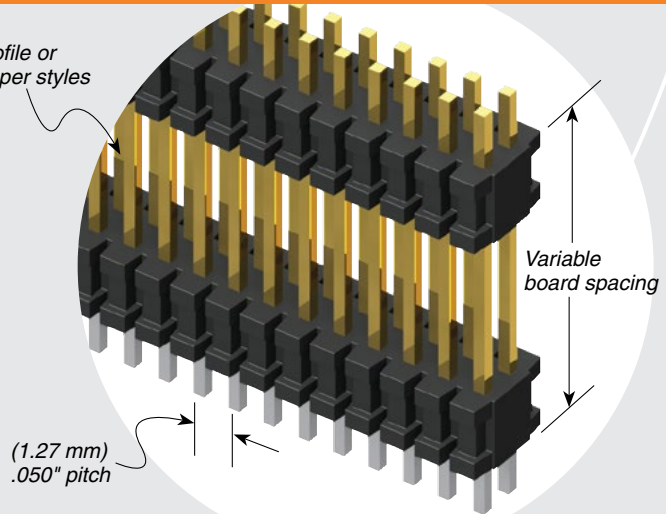
For complete scope of recognitions see www.samtec.com/quality



Board Mates: CLP, FLE

Cable Mates: FFSD

Low-profile or skyscraper styles



ALSO AVAILABLE (MOQ Required)

- Smaller stack heights
- Contact Samtec.

FW	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	D	STACKER HEIGHT	POST HEIGHT	OPTION
	02 thru 50	Specify LEAD STYLE from chart	-F = Gold flash on post, Matte Tin on tail -L = 10 μm (0.25 μm) Gold on post, Matte Tin on tail -G = 10 μm (0.25 μm) Gold on post, Gold flash on tail		-"XXX" = Stacker Height (in inches) Example: -250 = (6.35 mm) .250"	-"XXX" = Post Height (in inches) (1.65 mm) .065" minimum Example: -065 = (1.65 mm) .065"	-ES = End Shroud (-075 post height only. Mates only with CLP.) (5.46 mm) .215" to (15.49 mm) .610" stacker height only, 9 pins/row minimum -EP = End Shroud with Guide Post (-075 post height only. Mates only with CLP.) (5.46 mm) .215" to (15.49 mm) .610" stacker height only, 9 pins/row minimum

LEAD STYLE	TAIL (B)
-01	(1.14) .045
-02	(1.91) .075
-04	(2.29) .090

Notes: For added mechanical stability, Samtec recommends mechanical board spacers be used in applications with gold or selective gold plated connectors. Contact ipg@samtec.com for more information.

This Series is non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.